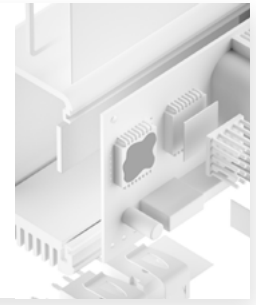


# SILICONE-FREE GAP-FILLER/PUTTY TGL-U-NS HALA

dispensable

TGL-U-NS is an electrically insulating thermally conductive, highly viscous dispensable silicone-free form-in-place gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. The ready-made compound does not require an additional crosslinking process. Due to the specific formulation and filling with ceramic particles the material has a very high thermal conductivity. After dispensing the viscoplastic material leads to an optimum thermal contact at no pressure. By its use the total thermal resistance is minimised.



## PROPERTIESEN

- Dispensable
- Almost zero pressure at assembly due to viscoplasticity
- Thermal conductivity: 4.0 W/mK
- Ready-made, no additional crosslinking required

## AVAILABILITY

- Cartridge 330 ml
- Others on request

## APPLICATION EXAMPLES

Thermal link of:

- SMD packages
  - Through-hole vias
  - RDRAMs memory modules
  - Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications / Laptops / Medicine engineering / Industrial PCs / 5G Telecommunication equipment

PROPERTY	UNIT	TGL-U-NS
<b>MATERIAL</b>		
		Ceramic filled silicone-free compound
Colour		Grey
Density	g/cm <sup>3</sup>	2.9
Viscosity (@ 0,5 1/s) (@ 1,0 1/s)	Pas	3,300 2,500
Shelf Life (unopened, dry storage conditions @ 5–30°C)	Months	6
UL Flammability (Equivalent)	UL 94	V0
RoHS Conformity	2015 / 863 / EU	Yes
<b>THERMAL</b>		
Thermal Conductivity <sup>1</sup>	W/mK	4.0
Operating Temperature Range	°C	- 40 to + 125
<b>ELECTRICAL</b>		
Dielectric Strength	kV / mm	8
Volume Resistance	Ohm - cm	1.0 x 10 <sup>9</sup>
Dielectric Constant	@ 500 MHz / @ 1 GHz	8.98 / 8.88

Measurement technique according to: <sup>1</sup>ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.